**AI TECHNOLOGY INC**
**70 Washington Road**
**Princeton Jct., NJ 08550**
**(609) 799-9388 fax (609) 799-9308**
**E-Mail: ait@aitechnology.com**
**Internet: http://www.aitechnology.com**

**PRIMA-BOND**

# ME7155

**Stress Free**
**Thermally Conductive**
**Reworkable**
**Epoxy Paste Adhesive**

**IDEAL FOR:**

**High Power Die Attach**
**Substrate and Component Reworkability**
**Mismatched CTE's**

## TYPICAL PROPERTIES*

| | |
|---|---|
| **Electrical Resistivity ( 150 ºC/ 60 minute )** | **>1x10 $^{14}$ ohm-cm** |
| **Dielectric Strength (Volts/mil)** | **>750** |
| **Glass Transition Temp.(ºC)** | **-25 ±10%** |
| **Current Carrying Capabilities** | **N/A** |
| **Lap-Shear Strength** | **>800 psi** |
| | **>5.5 N/mm²** |
| **Device Push-off Strength** | **>1500 psi** |
| | **>10.3 N/mm²** |
| **Hardness (Type)** | **80 (A) ±10%** |
| **Cured Density (gm/cc)** | **2.3 ±10%** |
| **Thermal Conductivity** | **12 Btu-in/hr-ft²-ºF ±10%** |
| | **1.7 W/m-C ±10%** |
| **Linear Thermal Expansion Coeff. (ppm/ºC)** | **130 ±15%** |
| **Maximum Continuous Operation Temp. (ºC)** | **<150** |
| **Pot Life** | |
| **Avg. Viscosity(0.5 rpm, 24ºC) (Brookfield DV-1,spindle CP51)** | **275,000 cp ±20%** |
| **Thixotropic Index** | |

* Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is intended to be used in manufacturing and in the final product.

**DESCRIPTION:**

ME7155 is a medium bond strength, stress absorbing, thermally conductive adhesive paste. ME7155 exhibits outstanding flexibility for bonding materials having highly mismatched CTE's (i.e., alumina to aluminum, silicon to copper). The high thermal conductivity of this material makes it useful for bonding high-powered, large area die and components.

It can be readily reworked at 80-100ºC.

**AVAILABILITY:**

ME7155 is available in syringes for automatic needle dispense applications or in jars.

**APPLICATION PROCEDURES:**

( 1 ) Thaw for 30 minutes before opening jar..

( 2 ) Dispense adhesive onto clean substrate.

( 3 ) Pre-bake dispensed adhesive at 60ºC for 30 to 60 minutes to achieve optimum bonding. Pre- bake not needed in all applications.**

( 4 ) Cure according to one of the recommended schedules.

**CURE SCHEDULES:**

| Temperature | Time | Pressure |
|---|---|---|
| 80ºC | 8 hr | |
| 100ºC | 4 hr | |
| 125ºC | 2 hr | |
| 150ºC | 1 hr | |

Viscosity updated in this current TDS version. Everything else remians the same.

**SHELF LIFE:**

| Storage temperature | Shelf Life |
|---|---|
| -40ºC | 1 yr |

CAUTION: This product may cause skin irritation. Avoid skin contact. If contact does occur, wash immediately with soap and water. Please refer SDS for more details.